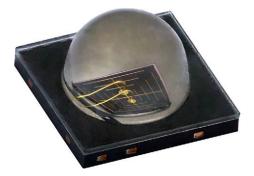
# VSMY98545



**Vishay Semiconductors** 

## High Power Infrared Emitting Diode, 850 nm, Surface Emitter Technology



### DESCRIPTION

As part of the <u>SurfLight</u><sup>TM</sup> portfolio, the VSMY98545 is an infrared, 850 nm emitting diode based on surface emitter technology with high radiant power and high speed, molded in low thermal resistance SMD package with lens. A 42 mil chip provides outstanding low forward voltage and allows DC operation of the device up to 1.5 A.

### FEATURES

- Package type: surface mount
- Package form: high power SMD with lens
- Dimensions (L x W x H in mm): 3.85 x 3.85 x 2.24
- Peak wavelength:  $\lambda_p = 850 \text{ nm}$
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity:  $\phi = \pm 45^{\circ}$
- Low forward voltage
- Designed for high drive currents: up to 1.5 A (DC) and up to 5 A pulses
- Low thermal resistance: R<sub>thJP</sub> = 10 K/W
- Floor life: 168 h, MSL 3, according to J-STD-020
- · Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### **APPLICATIONS**

- Infrared illumination for CMOS cameras (CCTV)
- Illumination for cameras (3D gaming)
- Machine vision
- Bio identification

### PRODUCT SUMMARY

COMPONENT	l <sub>e</sub> (mW/sr)	φ <b>(deg)</b>	λ <sub>p</sub> (nm)	t <sub>r</sub> (ns)
VSMY98545	380	± 45	850	15

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	ODE PACKAGING REMARKS		PACKAGE FORM	
VSMY98545	Tape and reel	MOQ: 600 pcs, 600 pcs/reel	High power with lens	

Note

• MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T <sub>amb</sub> = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V <sub>R</sub>	5	V	
Forward current		I <sub>F</sub>	1.5	A	
Peak forward current	$t_p/T = 0.5, t_p = 100 \ \mu s$	I <sub>FM</sub>	2	A	
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	5	A	
Power dissipation		Pv	3.5	W	
Junction temperature		Tj	115	°C	
Operating temperature range		T <sub>amb</sub>	-40 to +85	°C	
Storage temperature range		T <sub>stg</sub>	-55 to +100	°C	
Soldering temperature	According to Fig. 10, J-STD-20	T <sub>sd</sub>	260	°C	
Thermal resistance junction / pin	JESD 51	R <sub>thJP</sub>	10	K/W	

1 For technical questions, contact: <u>emittertechsupport@vishay.com</u> Document Number: 81223

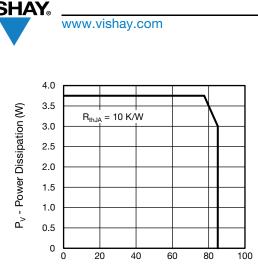


RoHS

FREE

GREEN

(5-2008)



T<sub>amb</sub> - Ambient Temperature (°C)

Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

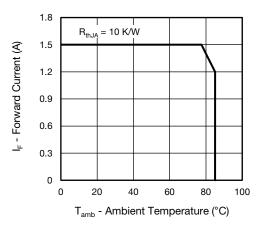


Fig. 2 - Forward Current Limit vs. Ambient Temperature

<b>BASIC CHARACTERISTICS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 1 A, t <sub>p</sub> = 20 ms	V <sub>F</sub>	-	1.8	2.5	V
	I <sub>F</sub> = 5 A, t <sub>p</sub> = 100 μs	V <sub>F</sub>	-	2.6	-	V
Temperature coefficient of $V_F$	I <sub>F</sub> = 100 mA	TK <sub>VF</sub>	-	-1.5	-	mV/K
Reverse current	V <sub>R</sub> = 5 V	I <sub>R</sub>	Not designed for reverse operation			μA
Radiant intensity	I <sub>F</sub> = 1 A, t <sub>p</sub> = 20 ms	Ι <sub>e</sub>	250	380	-	mW/sr
	I <sub>F</sub> = 5 A, t <sub>p</sub> = 100 μs	l <sub>e</sub>	-	1600	-	mW/sr
Radiant power	I <sub>F</sub> = 1 A, t <sub>p</sub> = 20 ms	φ <sub>e</sub>	-	800	-	mW
Temperature coefficient of $\phi_{e}$	I <sub>F</sub> = 100 mA	ΤΚφ <sub>e</sub>	-	-0.13	-	%/K
Angle of half intensity		φ	-	± 45	-	deg
Peak wavelength	I <sub>F</sub> = 1 A	λρ	-	850	-	nm
Spectral bandwidth	I <sub>F</sub> = 1 A	Δλ	-	35	-	nm
Temperature coefficient of $\lambda_p$	I <sub>F</sub> = 100 mA	ΤΚλ <sub>p</sub>	-	0.2	-	nm/K
Rise time	I <sub>F</sub> = 1 A	t <sub>r</sub>	-	15	-	ns
Fall time	I <sub>F</sub> = 1 A	t <sub>f</sub>	-	18	-	ns



## BASIC CHARACTERISTICS (T<sub>amb</sub> = 25 °C, unless otherwise specified)

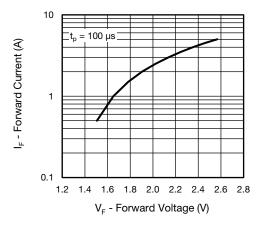


Fig. 3 - Forward Current vs. Forward Voltage

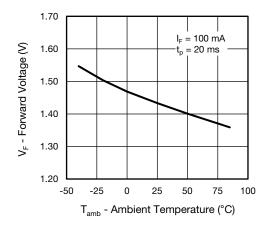


Fig. 4 - Forward Voltage vs. Ambient Temperature

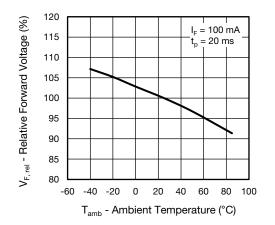


Fig. 5 - Relative Forward Voltage vs. Ambient Temperature

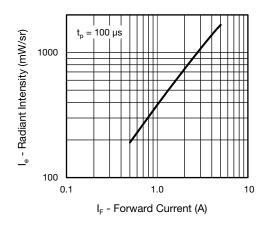


Fig. 6 - Radiant Intensity vs. Forward Current

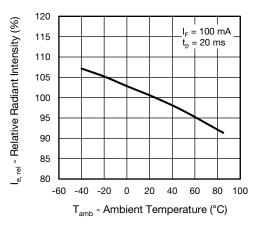


Fig. 7 - Relative Radiant Intensity vs. Ambient Temperature

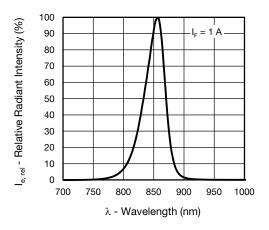
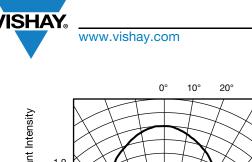
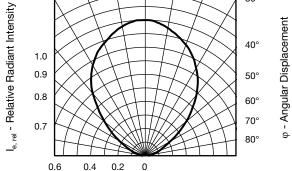


Fig. 8 - Relative Radiant Power vs. Wavelength

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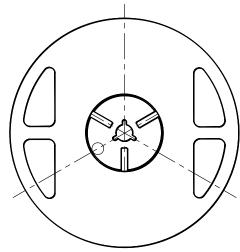


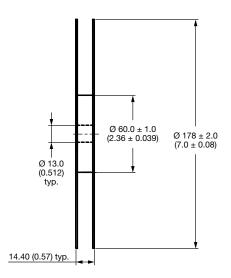


30°

Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

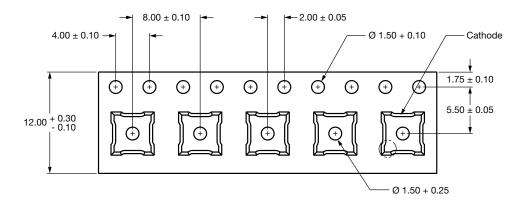
#### TAPING DIMENSIONS in millimeters





#### Notes

- Empty component pockets sealed with top cover tape.
- 7 inch reel 600 pieces per reel.
- The maximum number of consecutive missing lamps is two.
- In accordance with ANSI / EIA 481-1-A-1994 specifications.



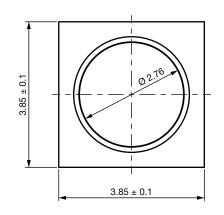
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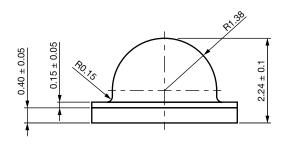
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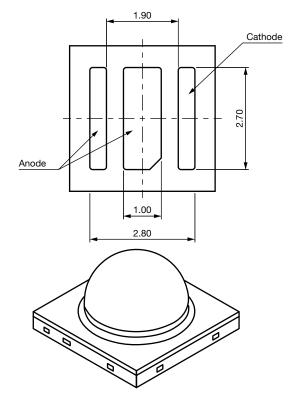




## **PACKAGE DIMENSIONS** in millimeters

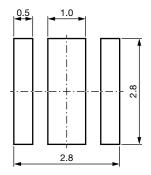




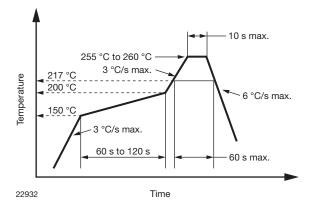


#### Notes

- Tolerance is  $\pm$  0.10 mm (0.004") unless otherwise noted.
- Specifications are subject to change without notice.



## SOLDER PROFILE



www.vishay.com

Fig. 10 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

### DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions:  $T_{amb} < 30\ ^\circ C,\ RH < 60\ \%$ 

Moisture sensitivity level 3, according to J-STD-020B

### DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.



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